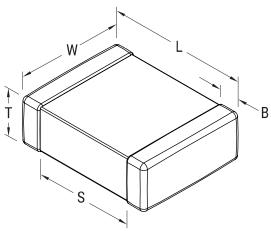


C0603C510MATAC7411

SMD Comm X8G HT150C, Ceramic, 51 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm





<u> </u>	S	AEC-Q200 Typical Compone
	Shelf Life MSL	
Dimensions		Specifications
Chip Size	0603	Capacitance
L	1.6mm +/-0.15mm	Measurement Co
W	0.8mm +/-0.15mm	Tolerance

0.5mm MIN

0.35mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

s

В

General Information			
Series	SMD Comm X8G HT150C		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	3.7 mg		
Shelf Life	78 Weeks		
MSL	1		

Specifications	
Capacitance	51 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	20%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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